

Vishay Siliconix

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)		
- 30	0.0125 at V _{GS} = - 10 V	- 14.9	29.5 nC		
- 30	0.0205 at $V_{GS} = -4.5 \text{ V}$	- 11.6	29.5 110		

FEATURES

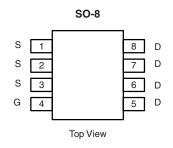
- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested



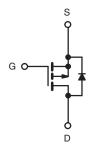
RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch







P-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	- 30	V	
Gate-Source Voltage	V_{GS}	± 25	V	
	T _C = 25 °C		- 14.9	
Continuous Prain Current (T = 150 °C)	T _C = 70 °C		- 11.9	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	- 10.9 ^{a, b}	
	T _A = 70 °C		- 8.6 ^{a, b}	
Pulsed Drain Current	I _{DM}	- 60	Α	
Continuous Source-Drain Diode Current	T _C = 25 °C	1	- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.2 ^{a, b}	
Avalanche Current	1 0 4 mal 1	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		5.0	
Mariana Paran Dissination	T _C = 70 °C	ь —	3.2	14/
Maximum Power Dissipation	T _A = 25 °C	P _D	2.7 ^{a, b}	W
	T _A = 70 °C		1.7 ^{a, b}	
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R_{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R_{thJF}	20	25	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.

Si4825DDY

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SPECIFICATIONS T _J = 25 °C Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static	- ,			-71-			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 34		mV/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.3		°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 1.4		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	I	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	- 1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	- 5		- 5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
Dunin Course On Otata Basistanas	R	V _{GS} = - 10 V, I _D = - 10 A		0.010	0.0125	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -8 \text{ A}$		0.0165	0.0205		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2550		pF	
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		455			
Reverse Transfer Capacitance	C _{rss}			390			
Total Gate Charge	Q _g	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		57	86	nC	
Total date onlarge				29.5	45		
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		8		110	
Gate-Drain Charge	Q_gd			22			
Gate Resistance	R_{g}	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		12	24		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70		
Fall Time	t _f			9	18	ns	
Turn-On Delay Time	t _{d(on)}			48	80	113	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		92	160		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		34	60		
Fall Time	t _f	1		19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			- 4.1	Α	
Pulse Diode Forward Current	I _{SM}				- 60		
Body Diode Voltage	V_{SD}	$I_{S} = -3 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns	
Body Diode Reverse Recovery Charge	Q_{rr}	I _F = - 10 A, dl/dt = 100 A/μs, T _{.1} = 25 °C		16	27	nC	
Reverse Recovery Fall Time	t _a	i _F = 10 Λ, αι/αι = 100 Λ/μο, 1 _J = 25 °C		12		ns	
Reverse Recovery Rise Time	t _b			15			

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

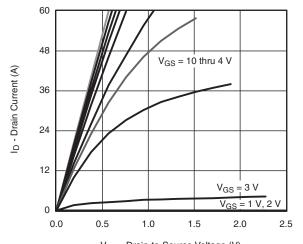
b. Guaranteed by design, not subject to production testing.

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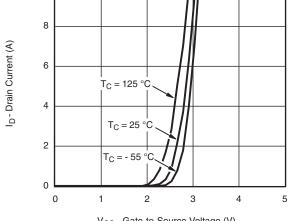
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

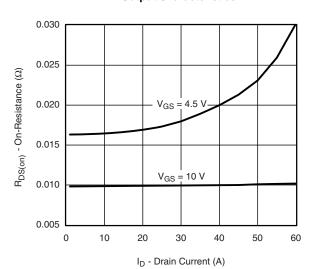


V_{DS} - Drain-to-Source Voltage (V)

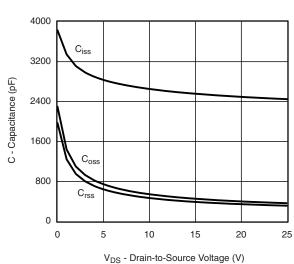
Output Characteristics



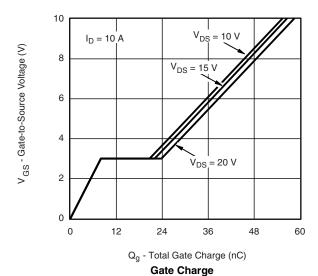
V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**

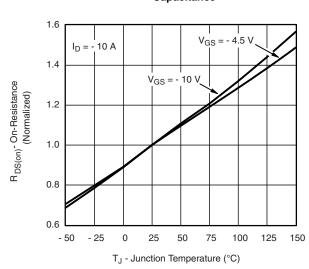


On-Resistance vs. Drain Current



Capacitance





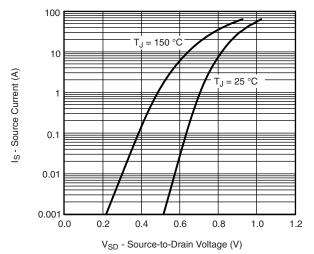
On-Resistance vs. Junction Temperature

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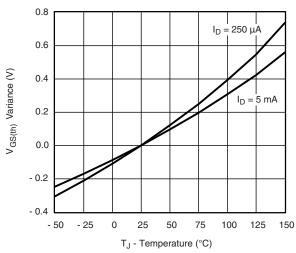
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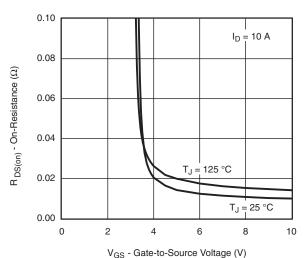
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



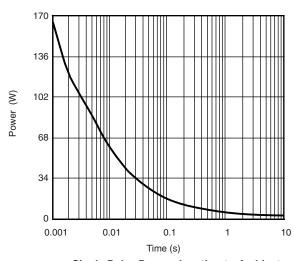
Source-Drain Diode Forward Voltage



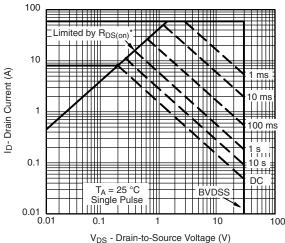
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



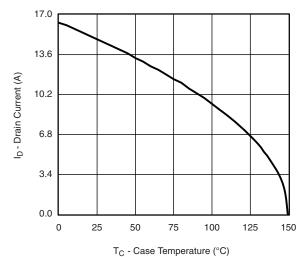
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area

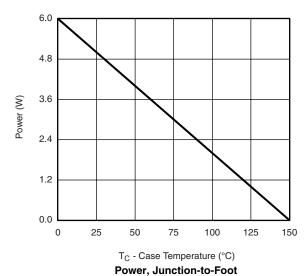


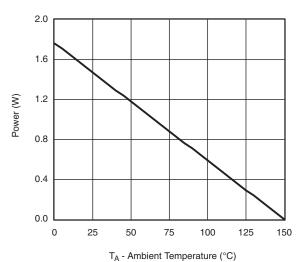
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MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





Power Derating, Junction-to-Ambient

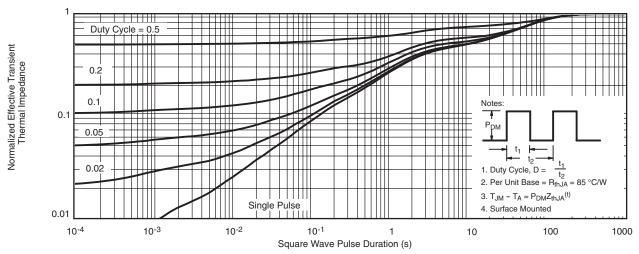
 $^{^*}$ The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package

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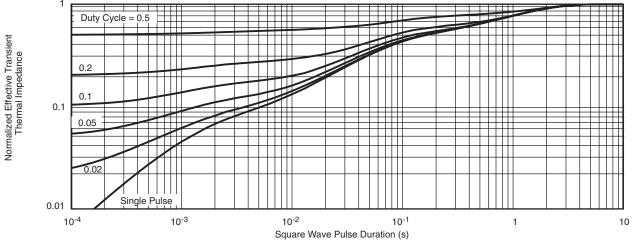
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS INCHES			HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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